

## Green Silicon Carbide Powder

**Color:**Green

**Content:**>98%

**Basic Mineral:** $\alpha$ -SiC

**Crystal form:**Hexagonal crystal

**Mohs hardness:**3300kg/mm<sup>3</sup>

**True density:**3.2g/mm<sup>3</sup>

**Bulk density:**1.2-1.6g/mm<sup>3</sup>

**Specific gravity:**3.20-3.25



Professional green silicon carbide micro powder grit manufacturer. It adopts the siphon method grading technology, can produce the finest standard grains to 0.5um in the micro powder industry.

The green silicon carbide powder takes the petroleum coke and high-quality silica as the main raw materials, add table salt as an additive, produced by smelting at a high temperature about 2200℃ through resistance furnace. The hardness of the green silicon carbide micro grit is between corundum and diamond, mechanical strength is higher than corundum. In addition to processing cemented carbide, glass, ceramics and non-metallic materials, it can also process semiconductor materials, high-temperature silicon carbide heating elements, far-infrared source substrates, etc.

### Advantages

- ① Low density
- ② High strength
- ③ High temperature strength (reactive bonding)
- ④ Oxidation resistance (reaction bonding)
- ⑤ Excellent thermal shock resistance
- ⑥ High hardness and good wear resistance
- ⑦ Excellent chemical resistance.

## Specifications and Chemical

|                |   |       |                                |
|----------------|---|-------|--------------------------------|
| Specifications | 240#, 280#, 320#, 360#, 400#, 500#, 600#, 700#, 800#, 1000#, 1200#, 1500#, 2000#, 2500#, 3000#, 4000#, 6000#, 8000#, 10000#, 12500# |       |                                |
| Grains         | Chemical composition(%)   |       |                                |
|                | SiC   | F.C   | Fe <sub>2</sub> O <sub>3</sub> |
| 240#-2000#     | ≥99   | ≤0.30 | ≤0.20                          |
| 2500#-4000#    | ≥98.5   | ≤0.50 | ≤0.30                          |
| 6000#-12500#   | ≥98.1   | ≤0.60 | ≤0.40                          |

## Application

- ① Cutting and grinding of the solar wafers, semiconductor wafers, and quartz chips.
- ② Polishing of crystal and pure grain iron.
- ③ Precision polishing and sandblasting of ceramics and special steel.
- ④ Cutting, free grinding and polishing of fixed and coated abrasive tools.
- ⑤ Grinding the non-metallic materials such as glass, stone, agate and high-grade jewellery jade.
- ⑥ Manufacturing the advanced refractory materials, engineering ceramics, heating elements and thermal energy elements, etc.